

**HIGH DENSITY ELECTRONICS ASSEMBLY AND METHOD**

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Abstract of the Disclosure

A high density electronics assembly which is highly modular in nature, thereby allowing a user to configure the assembly as desired for particular applications. The assembly also advantageously utilizes electronics inserts that are standardized across varying configurations, thereby obviating the need for different inserts for different applications. In one exemplary 10 embodiment, the assembly comprises a low-profile Digital Subscriber Line (DSL) splitter apparatus, having a plurality of splitter circuits disposed within a housing structure in high density. Methods for manufacturing and configuring the assembly are also disclosed.

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